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IEET

U.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 08244.0027
CUSTOMER NUMBER: 22,852

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

ATTN. BOX ASSIGNMENTS

OIPE JC152
JUL 2 5 2001
PATENT & TRADEMARK OFFICE

07/25/01

1. Name of conveying party(ies):

Suk-Jae LEE

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Hyundai Electronics Industries Co., Ltd.

Internal Address:

Street Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea

City:

State:

Zip Code:

Additional name(s) & Address(es) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other

Execution Date: April 20, 2001

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application:

A. Patent Application Number(s):

09/740,945

B. Patent Number(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

07/31/2001 TDIAZ1 00000095 09740945
01 FC:581 40.00 OP

Street Address: 1300 I Street, N.W.

City: Washington

State: DC Zip: 20005-3315

6. Total number of applications and registrations involved: 1

7. Total fee (37 CFR 3.41): $40

☒ Enclosed (Please charge deficiency to deposit account)

☐ Authorized to be charged to deposit account

8. Deposit account number: 06-0916

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman
Reg. No. 25,961

Signature

July 25, 2001
Date

Total number of pages including cover sheet, attachments and documents: 2

SOLE/JOINT INVENTION
(Worldwide Rights)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled METHOD FOR MANUFACTURING A COPPER INTERCONNECTION IN SEMICONDUCTOR MEMORY DEVICE

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on December 21, 2000 (Serial No. 09/740,945); and

WHEREAS, **HYUNDAI ELECTRONICS INDUSTRIES CO., LTD.**, a corporation of **REPUBLIC OF KOREA** whose post office address is **San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea** (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar ($1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto theAssignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional application Serial No. ____________, filed ____________ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof, and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

County of Korea)
) ss.
State of Kyoungki-do)

Name LEE, SUK-JAE
Address San 136-1, Ami-ri, Bubal-eub, Ichon-shi
Kyoungki-do 467-860, Republic of Korea

SIGNATURE ____________
DATE April 20, 2001

Subscribed and sworn to before me this _____ day of ____________, 20___.
____________, Notary Public

County of ____________)
) ss.
State of ____________)

Name ____________
Address ____________
____

SIGNATURE ____________
DATE ____________

Subscribed and sworn to before me this _____ day of ____________, 20___.
____________, Notary Public